



**AS4C8M32S-7BCN / AS4C8M32S-6BIN**

Part Number:		<b>AS4C8M32S-7BCN / AS4C8M32S-6BIN</b>								
Part Weight:		350mg								
No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt % of Total unit wt	PPM	
1	Substrate	HL832NX / AUS308	162.706	Nickel	7440-02-0	0.87%	1.416	0.40	8700	
				Gold	7440-57-5	0.11%	0.179	0.05	1100	
				Continuous Filament Fiber Glass	65997-17-3	29.27%	47.624	13.61	292700	
				Copper	7440-50-8	27.65%	44.988	12.85	276500	
				Bismaleimide	13676-54-5 / 25722-66-1	15.23%	24.780	7.08	152300	
				Epoxy Resin	9003-36-5	19.00%	30.914	8.83	190000	
				Inorganic filler	21645-51-2	2.41%	3.921	1.12	24100	
				Talc containing no asbestiform fibers	14807-96-6	0.15%	0.244	0.07	1500	
				Morpholine derivative	Trade secret	0.15%	0.244	0.07	1500	
				Barium Sulfate	7727-43-7	1.69%	2.750	0.79	16900	
				Dipropylene glycol monomethyl ether	34590-94-8	0.29%	0.472	0.13	2900	
2	Mold compound	G770	119.747	Silica , amorphous	7631-86-9	3.18%	5.174	1.48	31800	
				Epoxy Resin A	Trade secret	3.00%	3.592	1.03	30000	
				Epoxy Resin B	Trade secret	3.00%	3.592	1.03	30000	
				Phenol Resin A	Trade secret	3.00%	3.592	1.03	30000	
				Phenol Resin B	Trade secret	3.00%	3.592	1.03	30000	
				Metal Hydroxide	Trade secret	1.50%	1.796	0.51	15000	
				Carbon Black	1333-86-4	0.30%	0.359	0.10	3000	
				Silica Fused	60676-86-0	70.90%	84.901	24.26	709000	
				Silica Fused	7631-86-9	15.00%	17.962	5.13	150000	
Silica, crystalline	14808-60-7	0.30%	0.359	0.10	3000					
3	Film	EH-900	0.108	Epoxy Resin	Trade Secret	15.00%	0.016	0.00	150000	
				Phenol Resin	Trade Secret	15.00%	0.016	0.00	150000	
				SiO2 Filler	Trade Secret	5.00%	0.005	0.00	50000	
				(Meta)Acrylic Copolymer	Trade Secret	65.00%	0.070	0.02	650000	
4	Film	EM-500M2A	0.039	Solid Epoxy Resin	Trade Secret	12.50%	0.005	0.00	125000	
				Phenol Resin	Trade Secret	12.50%	0.005	0.00	125000	
				Fused Silica	60676-86-0	35.00%	0.014	0.00	350000	
				Synthetic Rubber	Trade Secret	40.00%	0.016	0.00	400000	
5	Solder Ball	96.5Sn3Ag0.5Cu	50.748	Sn	7440-31-5	96.50%	48.972	13.99	965000	
				Ag	7440-22-4	3.00%	1.522	0.43	30000	
				Cu	7440-50-8	0.50%	0.254	0.07	5000	
6	Gold wire	Au	1.19	Gold	7440-57-5	99.99%	1.190	0.34	999900	
				Impurity	Trade Secret	0.01%	0.000	0.00	100	
7	Die	Chip	15.462	Silicon	7440-21-3	100.00%	15.462	4.42	1000000	
			350				700.00%	350.000	100.00	7000000